# XV-112 MICRO PANEL





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## **Original instructions**

The German version of this document is the original instructions.

## Translations of the original instructions

All non-German editions of this document are translations of the original instructions.

#### **Editor**

Monika Jahn

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## 1 General

## 1.1 Purpose of these Operating Instructions

These Operating Instructions contain the information required for the correct and safe use of the MICRO PANELs XV-112. The Operating Instructions are part of the devices and must therefore be kept nearby.

These Operating Instructions describe all aspects of the devices: transport, installation, commissioning, operation, maintenance, storage and disposal. The operating system and the application software are not described.



Read Chapter 3 Safety regulations, 

9 before working with the device. This contains important information for your personal safety. This chapter must be read and understood by all persons working with this device.

## **⚠WARNING**



#### Incomplete copy of the Operating Instructions

Working with individual pages of these Operating Instructions may cause damage to property or personnel by failure to observe safety-related information.

Always work with the complete document.

## 1.2 Comments about this document

Please send any comments, recommendations or suggestions relating to this document to info-auto-mation@eaton.com.

### 1.3 Additional documentation

The following documents may be helpful in the use of the device in addition to this document:

- [1] MN04802013Z-EN Quick Start Guideline XV100 (commissioning the MICRO PANEL, establishing communication with the programming PC and creating projects with GALILEO and XSoft-CoDeSys-2)
- [2] MN05010007Z-EN System Description Windows CE (operation of the Windows CE operating system on MICRO PANELS)
- [3] MN05010009Z-EN System Description Networks in Brief (information on networks in general and on the integration of PCs and MICRO PANELs in networks)

The documents can be downloaded from:

- www.moeller.net, «Support» section
- www.eaton.eu (search document No. via search field of the home page)
- www.eaton-automation.com, «DOWNLOADS» section

- 1 General
- 1.3 Additional documentation

# 2 Device description

## 2.1 Function

MICRO PANELs XV-112 can be used as HMI devices or as integrated HMI/PLC devices.

## 2.2 Intended use

MICRO PANELs XV-112 are primarily used in machine and system building. They are designed exclusively for the visualization, operation and control of machines and systems. Any other use must be agreed beforehand with the manufacturer.

## 2.3 Device versions





Abb. 1 XV-112 5.7"

Abb. 2 XV-112 7.0"

MICRO PANELs XV-112 are available in the following versions:

Basic device	Display	Communication interfaces	XV-112 type
Version D:  1 Slot for 1 SD card Integrated interfaces:	Resistive touch, 5.7" TFT-LCD, 64k colors, VGA		XV-112-D6-57TVR
× Ethernet 100/10     × USB Device     × USB Host Communication interfaces	Resistive touch, 7.0" TFT-LCD, 64k colors, WVGA	2 × CAN <sup>1)</sup> 1 × RS232	XV-112-DB-70TWR

Tab. 1 Device versions

<sup>1)</sup> The CAN interfaces of XV-112-DB-... are electrically isolated. The CAN interfaces of all other device versions are **not** electrically isolated.

## 2 Device description

## 2.4 Package contents

#### 2.4 **Package contents**

The package contents of the MICRO PANELs XV-112 consist of the following:

Qty	Designation
1	MICRO PANEL: ■ XV-11257TVR or ■ XV-11270TWR
1	Power supply connector

Tab. 2 Package contents



If required, styluses in sets of 5 (ACCESSORIES-TP-PEN-5, Article No. 171192) and other accessories can be ordered. Please contact the supplier.

#### 2.5 **Accessories**

Different accessories are available. Use only original accessories.



Order the accessories required from your supplier.

#### 2.6 Designation

## **Nameplate**

A nameplate is fixed on the rear of the device in order to identify it. The nameplate contains the following information:

- Manufacturer address
- Type designation
- Power supply required
- Part no. (Part-No or Art.-No)
- Serial no.
- Time of manufacturing (week/year)
- Approval mark and information to the approval
- Arrangement of interfaces and operating elements
- Permissible mounting options (top edge «Top»)

## **Support**

To ensure fast and optimum support always provide the support personnel with the following information on the nameplate:

- Part no. (Part-No or Art.-No)
- Serial no.

# 3 Safety regulations

## 3.1 General

Hazards may still occur even though the device meets the current state of the art and complies with all recognized safety requirements.

The device must only be installed and commissioned in perfect technical condition and in compliance with this document.



Read this chapter before working with the device. This contains important information for your personal safety. This chapter must be read and understood by all persons working with this device.

- 3 Safety regulations
- 3.2 Meaning of symbols

## 3.2 Meaning of symbols

The following symbols are used in this document according to the hazard level described:

## **⚠** DANGER



## Signal word DANGER

Indicates an imminently hazardous situation which, if not avoided, will result in death or serious injury.

## **⚠WARNING**



#### Signal word WARNING

Indicates a potentially hazardous situation which, if not avoided, could result in death or serious injury.

## **A**CAUTION



## **Signal word CAUTION**

Indicates a potentially hazardous situation which, if not avoided, could result in minor or moderate injury.

## **CAUTION**



## Signal word CAUTION without safety alert symbol

Indicates a situation which, if not avoided, could result in material damage.



## Indicates useful information.

The danger symbol used and the text indicate the actual danger and the related preventative measures.

## 3.3 Mandatory requirements, personnel

## 3.3.1 Work safety

All applicable work safety regulations (in-house and national) must be observed.

#### 3.3.2 Qualification of personnel

The personnel responsible for installation, operation, maintenance and service must be adequately qualified. These persons must be sufficiently trained or instructed and they must be informed of all hazards and risks associated with the device.

## 3.3.3 Operating Instructions

It must be ensured that any person working with the device in any phase of its lifespan has read and understood the relevant sections of the Operating Instructions.

#### **⚠WARNING**



## Incomplete copy of the Operating Instructions

Working with individual pages of these Operating Instructions may cause damage to property or personnel by failure to observe safety-related information.

Always work with the complete document.

## 3.3.4 Installation, maintenance and disposal

It must be ensured that the device is properly connected, mounted, maintained and disposed of in compliance with all relevant standards and safety regulations.

## 3.3.5 Prohibited use

The implementation of safety functions (relating to the protection of personnel and machinery) using the device is prohibited.

## 3 Safety regulations

## 3.3 Mandatory requirements, personnel

## 3.3.6 Requirements for proper operation

The following points must be observed so that the device meets the contractual requirements:

- Only qualified personnel may work with the device.
- These persons must have read the Operating Instructions and must observe the requirements described.
- The ambient conditions stated must be observed. See Chapter 9.9 Ambient conditions, 

  53.
- The maintenance work must be carried out correctly.
- Potentially explosive atmosphere, Zone 22: The ground resistance of accessible metal parts must be less than 10<sup>9</sup> ohms.

No liability is accepted for damage, consequential damage and accidents caused by the following:

- Failure to observe work safety regulations
- Failure or malfunction of the device
- Improper handling or use
- Failure to observe the Operating Instructions
- Conversions, modifications and repairs to the device



### 3.4 Device related hazards

## **▲** DANGER



#### **Explosion hazard**

Death, serious injury or material damage may occur if an electrical plug connection is removed in a potentially explosive atmosphere during operation or if the device is subjected to hazardous knocks.

- ▶ Only use the device in the following environments:
  - Environments not subject to explosion hazards
  - Potentially explosive atmosphere, Zone 22 (according to ATEX 94/9/EC)
- ▶ Potentially explosive atmosphere, Zone 22:

The ground resistance of accessible metal parts must be less than 10<sup>9</sup> ohms.

- ➤ When used in a potentially explosive atmosphere, Zone 22, the environment has to be designed to avoid any bunch discharge.
- Prevent the device from being subjected to hazardous knocks.
- Only operate the device in potentially explosive atmospheres if it is correctly mounted.
- Switch off the device before removing the plug connections.

#### **⚠WARNING**



#### Live parts in the device

When the device is opened, there is a risk of electric shock if live parts are touched.

➤ The device must not be opened.

#### **⚠WARNING**



#### Potential equalization currents

Large equalization currents between the protective ground systems of different devices may cause operational malfunctions due to signal interference and may even cause fires.

▶ If necessary, a potential equalization conductor should be installed parallel to the cable. This should have a cross-section that is a multiple of the cable shield.

## **ACAUTION**



#### Electrostatic discharge

Electrostatic discharge may damage or destroy electronic components.

- Avoid contact with components (such as connector pins) that are susceptible to electrostatic discharge.
- Discharge (by touching a grounded metal object) any static charge accumulated in your body before touching the device.

## **CAUTION**



#### Non-isolated interfaces

The device may be damaged due to potential differences.

▶ The GND terminals of all bus stations must be connected.

#### CAUTION



#### Sensitive resistive touch surface

Damage to the resistive touch due to the use of pointed or sharp objects.

- Only activate the resistive touch with your finger or a stylus.
- ➤ When wearing gloves, ensure that these are clean. They must not be covered with abrasive dust or sharp particles.

#### **CAUTION**



#### **Data loss**

During a write operation, the SD card may lose data or may be destroyed if it is removed or if there is a power failure.

- ▶ Only insert the SD card when the device is in a de-energized state.
- ▶ Avoid write operations to SD cards. Reasons:
  - The number of write cycles possible on SD cards is limited.
  - A power failure during write operations will most likely lead to loss of data.
- ▶ Only remove the SD card when the device is in a de-energized state.
- Before switching off, ensure that no software write operations to the SD card are in progress.

### **CAUTION**



## **Device condensation**

If the device is or was exposed to climatic changes (temperature fluctuation, air humidity) moisture can form on or in the device (device condensation). In this case, there is a risk of short-circuit.

- ▶ The device must **not** be switched on when device condensation is present.
- ▶ If condensation is present on the device, or if it was exposed to temperature fluctuations, it must be allowed to adjust to room temperature (do not expose the device to the direct heat of heating devices) prior to commissioning.

#### **CAUTION**



### **UV** light

When exposed to UV light, plastics can embrittle and the lifespan of the device is reduced.

Protect the device against direct sunlight and lamps with UV rays.

## **CAUTION**



## Cleaning the device

Damage to the device due to the use of pointed or sharp objects or by liquids.

- ▶ Do not use any pointed or sharp objects (e.g. knife) for cleaning.
- ▶ Do not use any aggressive or abrasive cleaning agent or solvent.
- ▶ Avoid any liquid entering the device (risk of short-circuit).

- 3 Safety regulations
- 3.4 Device related hazards

# 4 Operating and indication elements

## 4.1 Overview



Abb. 3 Operating and indication elements

The device has the following operating and indication elements:

Element		Function	
A	Display	Display operating and indication elements.	
В	Touch sensor	Resistive touch:  Detection of the actuation of the operating elements shown on the display. These devices are operated by touching the operating elements with your finger or with a stylus.	
С	SD slot 0	Slot for SD card.	
D	Control button	Function depends on the software used.	

Tab. 3 Operating and indication elements

- 4 Operating and indication elements
- 4.1 Overview

## 5 Installation

## 5.1 Safety regulations

Read Chapter 3 Safety regulations, 
9 before installing and commissioning the device.
This contains important information for your personal safety.

## 5 Installation

## 5.2 Requirements for the place of installation

## 5.2 Requirements for the place of installation

Approvals:

The device must only be used in locations that are approved for the device. See the markings on the nameplate and Chapter 9 Technical data, 

47.

Power supply:

The power supply must comply with the requirements stated in Chapter 9.5.1 Power supply, 15 51.

#### 5.2.1 Engineering conditions of acceptability by Underwriters Labaratories Inc. (UL)

For the approval in accordance with the standard UL 508, consideration must be given to the following:

- Ambient conditions:
  - Max. ambient temperature: 50°C
  - Pollution degree 2
- The screw terminals of the connector for the power supply must be tightened with a max. tightening torque of 0.6...0.8 Nm or 5...7 Lb. In.

#### 5.2.2 Requirements for the mounting position

The device is designed for back mounting in control cabinets, control panels or control desks. It can be mounted horizontally or vertically. The following requirements must be fulfilled when selecting a suitable mounting position:

- The device should not be exposed to direct sunlight (when exposed to UV light, plastic parts of the device can embrittle and the lifespan of the device is reduced).
- If the device is to be used in potentially explosive atmospheres, the device must not be subjected to hazardous knocks.
- The inclination angle for vertical mounting without forced ventilation must be max. ±45°.
- The operating elements on the service side of the device and the cable connections are accessible after the device has been mounted.
- The ambient conditions stated must be observed. See Chapter 9.9 Ambient conditions, 

  53.
- Sufficient ventilation (cooling) must be ensured by means of:
  - Clearance of at least 3 cm to the ventilation slots
  - Clearance of at least 15 cm from heat radiating components such as heavily loaded transformers
  - The expected temperatures should be within the permissible range. See Chapter 9.9 Ambient conditions, 

    § 53.
- Properties of the mounting surfaces:
  - Material thickness at the mounting cutout min. 3 mm
  - Flatness ≤ 0.5 mm (this requirement must also be fulfilled when the device is mounted!)

## 5.3 Interfaces

## **MARNING**



## Potential equalization currents

Large equalization currents between the protective ground systems of different devices may cause operational malfunctions due to signal interference and may even cause fires.

▶ If necessary, a potential equalization conductor should be installed parallel to the cable. This should have a cross-section that is a multiple of the cable shield.

## **CAUTION**



#### **Operational malfunctions**

Use of unsuitable or improperly prepared cables, as well as incorrect wiring will mean that neither the values stated in the technical data nor the electromagnetic compatibility (EMC) can be ensured.

- Only use cables prepared by specialists.
- ➤ The cables used must be prepared according to the interface description in this document.
- ➤ The wiring instructions for the relevant interface must be observed when wiring the device.
- ▶ Any generally applicable regulations and standards must be fulfilled.

## **CAUTION**



## Non-isolated interfaces

The device may be damaged due to potential differences.

▶ The GND terminals of all bus stations must be connected.

## 5.3 Interfaces

## 5.3.1 Overview of interfaces



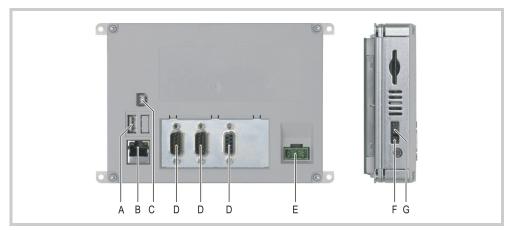


Abb. 4 Interfaces of the device

Int	erface	Interface description
A	USB Host	→ Chapter 5.3.7, 🗎 29
В	Ethernet	→ Chapter 5.3.5, 🗎 28
С	USB Device	→ Chapter 5.3.6, 🗎 29
D	Interfaces, depending on the device version:	
	CAN	→ Chapter 5.3.8, 🗎 30
	RS232 (System Port)	→ Chapter 5.3.4, 🗎 26
	RS485	→ Chapter 5.3.9, 🗎 33
Ε	Power supply	→ Chapter 5.3.3, 🗎 25
F	DIAG	Only for service tasks
G	Jumper UPD/RUN	Only for service tasks

Tab. 4 Overview of interfaces

#### 5.3.2

## Preparation of cables with D-Sub connector

The preparation of bus cables is an essential factor in ensuring reliable operation and electromagnetic compatibility (EMC).

## Wiring requirements

- The cables must be shielded.
- The cable shield must be made from a copper braid.
- The cable shield must make a low impedance connection with the connector casing over a large contact area. This is achieved by:
  - Use of metal or metallized connector casings with a cable clamp for strain relief.
  - The cable clamp must be screwed securely to the connector.

# Connecting the cable shield

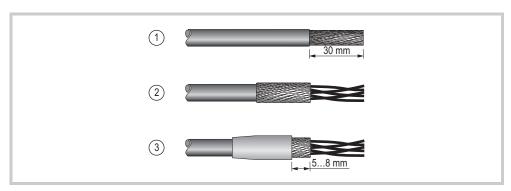


Abb. 5 Connecting the cable shield

- 1 Strip the cable end so that approx. 3 cm of the shield braid is exposed.
- 2 Fold back the shield braid over the cable shield.
- **3** Fit approx. 3 cm of heat shrinkable tubing over the folded back end of the shield braid or use a rubber grommet.
  - 5...8 mm of the shield braid must be exposed at the cable end.
  - The folded back shield braid end must be covered by the heat shrinkable tubing or by the rubber grommet.
- 4 Fit the D-Sub connector to the cable end:
  - The exposed metal shield braid must be clamped to the connector casing with the cable clamp.

## 5 Installation

## 5.3 Interfaces

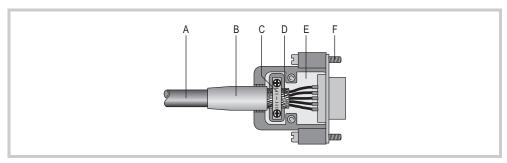


Abb. 6 Cable prepared with D-Sub connector

- A Cable with cable sheath
- B Heat shrinkable tubing or rubber grommet
- C Cable clamp

- D Shield braid
- E D-Sub connectorF Mounting screw UNC



The EMC values stated in the technical data (immunity and emission) can only be guaranteed by observing the prescribed cable preparation!

## 5.3.3 Power supply

The device is provided with an internal fuse and is protected against polarity reversal. The functional earthing terminal is connected to both the housing and the 0 V terminal. The device power supply is **not** electrically isolated.

The device requires a 24 VDC power supply from an AC/DC converter with safe isolation (SELV). For other power supply requirements see Chapter 9.5.1 Power supply, 

■ 51.

SELV (safety extra low voltage):
 Circuit in which no dangerous voltage is present, even in the event of a single fault.



Abb. 7 Power supply interface

## Wiring

Phoenix Contact MSTB 2.5/3-ST-5.08 connector, Phoenix order no. 1757022 is supplied with the device.

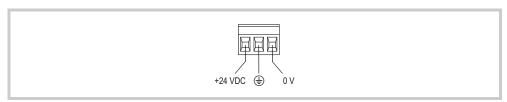


Abb. 8 Phoenix Contact MSTB 2.5/3-ST-5.08 connector (view from the wiring side)

Connection	Assignment
+24 VDC	+24 VDC power supply
?	Functional earthing connected to housing.  Does not have to be connected.  This connection can be used as protective earthing connection if the mounting environment requires this.
0 V	0 V power supply (connected to ⊕)

Tab. 5 Assignment of connector

■ The following must be observed when the connector wiring is prepared:

Preparing the wiring of the connector		
Terminal type Pluggable screw terminal		
Cross-section	<ul> <li>min. 0.75 mm<sup>2</sup> / max. 2.5 mm<sup>2</sup> (lead or wire)</li> <li>min. AWG18 / max. AWG12</li> </ul>	
Stripping length	7 mm	
Max. tightening torque	0.60.8 Nm / 57 Lb. In.	

Tab. 6 Preparing the wiring of the connector

## 5.3 Interfaces

## 5.3.4 RS232 (System Port)

The RS232 interface is **not** electrically isolated. The GND pin is directly connected to the housing potential.

## **CAUTION**



#### Non-isolated interfaces

The device may be damaged due to potential differences.

▶ The GND terminals of all bus stations must be connected.

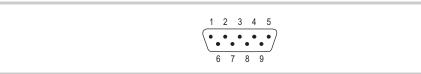


Abb. 9 RS232 interface (9-pin, D-Sub, male, UNC)

Pin	Signal	Assignment
1	DCD	Data Carrier Detected
2	RxD	Receive Data
3	TxD	Transmit Data
4	DTR	Data Terminal Ready
5	GND	Ground
6	DSR	Data Set Ready
7	RTS	Request to Send
8	CTS	Clear to Send
9	RI	Ring Indicator

Tab. 7 Pin assignment of the RS232 interface

- Shielded cables must be used.
- The maximum baud rate depends on the cable length:

Cable length	Max. baud rate
2.5 m	115200 Bit/s
5 m	57600 Bit/s
10 m	38400 Bit/s
15 m	19200 Bit/s
30 m	9600 Bit/s

Tab. 8 Relationship of cable length / baud rate

## Wiring

When preparing the cables, ensure that there is a low-resistance connection between the cable shield and the connector casing ( $\rightarrow$  Chapter 5.3.2,  $\blacksquare$  23).

## 5.3 Interfaces

## 5.3.5 Ethernet

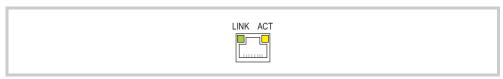


Abb. 10 Ethernet interface (RJ45 socket)

LED	Signal	Meaning
ACT (yellow)	flashes	Ethernet is active (data traffic)
LINK (green)	lit	Active network is connected and detected

Tab. 9 Control LEDs of the Ethernet interface

#### **Cable**

- Use shielded twisted pair cable (STP) for networking:
  - For device to device connection: crossover cable
  - For connecting to the hub/switch: 1:1 patch cable
- Maximum cable length: 100 m.

## **CAUTION**



## Forces acting on the Ethernet interface

Communication can be disturbed and the connection mechanics damaged if the Ethernet interface is exposed to severe vibration or the RJ45 plug connection is pulled.

- ▶ Protect the RJ45 connection from severe vibration.
- ▶ Protect the RJ45 connection from pulling on the socket.

5.3.6	USB Device

The USB Device interface supports USB 2.0.



Abb. 11 USB Device interface (USB Device, type B)

**Cable** 

- Only use shielded USB standard cable.
- Maximum cable length: 5 m.

## 5.3.7 USB Host

The USB Host interface supports USB 2.0.



Abb. 12 USB Host interface (USB Host, type A)

Cable

- Only use shielded USB standard cable.
- Maximum cable length: 5 m.

## 5.3 Interfaces

#### **CAN** 5.3.8

If the CAN interface is electrically isolated, depends on the device version. See Chapter 2.3 Device versions, 1 7.

## **CAUTION**



#### Non-isolated interfaces

The device may be damaged due to potential differences.

▶ The GND terminals of all bus stations must be connected.

Abb. 13 CAN interface (9-pin, D-Sub, male, UNC)

Pin	Signal	Assignment
1	-	nc
2	CAN-L	Bus line (dominant low)
3	CAN-GND	CAN Ground
4	-	nc
5	-	nc
6	GND	Optional CAN Ground
7	CAN-H	Bus line (dominant high)
8	-	nc
9	-	nc

Tab. 10 Pin assignment of CAN interface in accordance with CiA



- Pin 3 (CAN-GND) and 6 (GND) are connected internally in the device.
  - nc: Pins 1, 4, 5, 8 and 9 must not be connected.
  - The CAN bus drivers are fed internally with power.
  - No power supply for third-party devices is implemented on the CAN connector.

#### Wiring

Shielded twisted pair cables must be used.

Cable specifications	
Rated surge impedance	120 Ω
Permissible surge impedance	108132 Ω
Capacitance per unit length	< 60 pF/m
Core cross-section / max. cable length	$\geq$ 0.25 mm <sup>2</sup> / 100 m
	$\geq$ 0.34 mm <sup>2</sup> / 250 m
	$\geq$ 0.75 mm <sup>2</sup> / 500 m

Tab. 11 Cable specifications

The maximum baud rate depends on the cable length:

Cable length	Max. baud rate
25 m	1000 Kbit/s
50 m	800 Kbit/s
100 m	500 Kbit/s
250 m	250 Kbit/s
500 m	125 Kbit/s
500 m	100 Kbit/s (adjustable via software)
1000 m	50 Kbit/s
2500 m	20 Kbit/s
5000 m	10 Kbit/s

Tab. 12 Relationship of cable length / baud rate



- The use of repeaters is recommended with cables over 1000 m in length. Repeaters can also be used to implement electrical isolation. Refer to the documentation of the repeater manufacturer for further information.
  - Observe the recommendations of the CiA (CAN in Automation).
  - When preparing the cables, ensure that there is a low-resistance connection between the cable shield and the connector casing ( $\rightarrow$  Chapter 5.3.2,  $\stackrel{\triangle}{=}$  23).

## **CAN** bus topology

- A bus segment can connect up to 32 bus stations.
- Several bus segments can be linked via repeaters (bidirectional amplifiers). Refer to the documentation of the repeater manufacturer for further information.
- A bus segment must be provided with cable termination (120  $\Omega$ ) at both ends. These terminations must be connected in the connector, directly between pin 2 and 7.



- The bus segment must be terminated at both ends.
  - No more than two terminations must be provided on each bus segment.
  - Transmission faults can occur if operation is carried out without the correct termination.

## 5 Installation

## 5.3 Interfaces

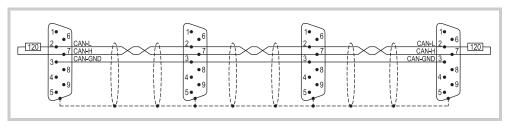


Abb. 14 Bus segment with four bus stations

#### 5.3.9 **RS485**

The RS485 interface is not electrically isolated. The GND pin is directly connected to the housing potential.

## **CAUTION**



#### Non-isolated interfaces

The device may be damaged due to potential differences.

▶ The GND terminals of all bus stations must be connected.

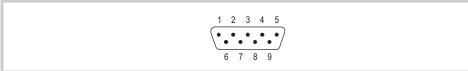


Abb. 15 RS485 interface (9-pin, D-Sub, male, UNC)

Pin	Signal	Assignment
1	-	nc
2	-	nc
3	В	Line B
4	-	nc
5	GND	Ground
6	-	nc
7	A	Line A
8	-	nc
9	-	nc

Tab. 13 Pin assignment of the RS485 interface



nc: Pins 1, 2, 4, 6, 8 and 9 must not be connected.

#### 5.3 Interfaces

#### Wiring

Shielded twisted pair cables must be used.

Cable specifications		
Rated surge impedance	120 Ω	
Permissible surge impedance	108132 Ω	
Max. cable length	1200 m	
Possible baud rates	9600 Bit/s	
	19200 Bit/s	
	38400 Bit/s	
	57600 Bit/s	
	115200 Bit/s	

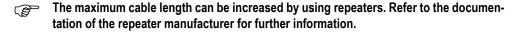
Tab. 14 Cable specifications



When preparing the cables, ensure that there is a low-resistance connection between the cable shield and the connector casing ( $\rightarrow$  Chapter 5.3.2,  $\stackrel{\triangle}{=}$  23).

## **RS485** topology

- A bus segment can connect up to 32 bus stations.
- Several bus segments can be linked via repeaters (bidirectional amplifiers). Refer to the documentation of the repeater manufacturer for further information.



A bus segment must be provided with cable termination (120  $\Omega$ ) at both ends. These terminations must be connected directly between pin 3 and 7 in the connector.



- The bus segment must be terminated at both ends.
  - No more than two terminations must be provided on each bus segment.
  - Transmission faults can occur if operation is carried out without the correct termination.

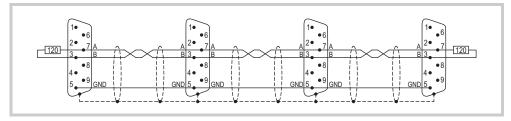


Abb. 16 Bus segment with four bus stations

## 5.4 Mounting

#### **CAUTION**



#### **Operational malfunctions**

Use of unsuitable or improperly prepared cables, as well as incorrect wiring will mean that neither the values stated in the technical data nor the electromagnetic compatibility (EMC) can be ensured.

- Only use cables prepared by specialists.
- The cables used must be prepared according to the interface description in this document.
- The wiring instructions for the relevant interface must be observed when wiring the device.
- ▶ Any generally applicable regulations and standards must be fulfilled.

#### **CAUTION**



#### **Device condensation**

If the device is or was exposed to climatic changes (temperature fluctuation, air humidity) moisture can form on or in the device (device condensation). In this case, there is a risk of short-circuit.

- ▶ The device must **not** be switched on when device condensation is present.
- ▶ If condensation is present on the device, or if it was exposed to temperature fluctuations, it must be allowed to adjust to room temperature (do not expose the device to the direct heat of heating devices) prior to commissioning.
- 1 Check the device for damage in transit.



The device must only be installed and commissioned in perfect technical condition and in compliance with this document.

- 2 Mount the device in the control cabinet, control panel or the control desk. See Chapter 5.4.1 Mounting the device, 36.
- 3 Connect the device as required.
  - Follow the instructions on wiring the relevant interface. See Chapter 5.3 Interfaces, 

    21.



The device is not provided with an On/Off switch. If the power supply is not provided with a switch, the device will start up (boot) as soon as it is connected to the power supply.

## 5.4 Mounting

## 5.4.1 Mounting the device



For mounting, various points have to be considered to make sure, the device works correctly and to prevent damage to the device. Contact your local supplier or Eaton technical support to get the drawings and data sheets with the relevant information for mounting listed below.

The following rules have to be taken into account when mounting:

- According to the display data sheet, no mechanical load may occur outside the active touch area of the resistive touch screen (edge area: ca. 2 ... 6 mm):
  - 5,7" devices: M0038097" devices: M003811
- According to the drawing «Basic Design Film for XV-112-... Front», positioning and size of the display cutout on the design film:
  - 5,7" devices: M0043317" devices: M004332
- Consider the following drawings and position the rear mounting device that the front of the touch screen is flush with the rear of the front film (e. g. between the front film and the touch screen must not be a space):
  - 5,7" devices:
    - M003507 (Dimension Drawing XV-112-57-1)
    - M004333 (Cutout for XV-112-70-1 Front Plate)
    - M004331 (Basic Design Film for XV-112-57 Front)
    - M004335 (Front Assembly)
  - 7" devices:
    - M003508 (Dimension Drawing XV-112-70-1)
    - M004334 (Cutout for XV-112-70-1 Front Plate)
    - M004332 (Basic Design Film for XV-112-70 Front)
    - M004335 (Front Assembly)

# 6 Operation

#### 6.1 Safety regulations



Read Chapter 3 Safety regulations, 

9 before working with the device. This contains important information for your personal safety.

#### **CAUTION**



#### Sensitive resistive touch surface

Damage to the resistive touch due to the use of pointed or sharp objects.

- Only activate the resistive touch with your finger or a stylus.
- ▶ When wearing gloves, ensure that these are clean. They must not be covered with abrasive dust or sharp particles.

#### **CAUTION**



#### **Device condensation**

If the device is or was exposed to climatic changes (temperature fluctuation, air humidity) moisture can form on or in the device (device condensation). In this case, there is a risk of short-circuit.

- ▶ The device must **not** be switched on when device condensation is present.
- ▶ If condensation is present on the device, or if it was exposed to temperature fluctuations, it must be allowed to adjust to room temperature (do not expose the device to the direct heat of heating devices) prior to commissioning.

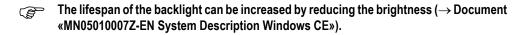
## 6 Operation

## 6.2 Starting the device

## 6.2 Starting the device

- 1 Energize the device.
  - The device will boot.
- 2 If the device does not boot up and/or if an error message appears while starting (booting) the device, see Chapter 7.4 Troubleshooting, 

  44.
- 3 Complete the following steps after initial commissioning (→ Document «MN05010007Z-EN System Description Windows CE»):
  - **3.1** Adjust the system settings of the device.
  - 3.2 Install the required application programs.



## 6.3 Switching off the device

1 De-energize the device.

#### 6.4 Inserting and removing an SD card

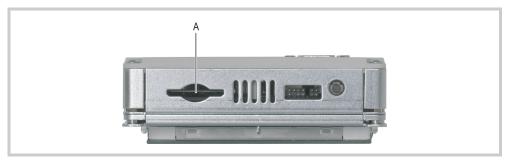


Abb. 17 SD slot (A)

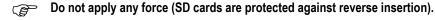
#### **CAUTION**



#### **Data loss**

During a write operation, the SD card may lose data or may be destroyed if it is removed or if there is a power failure.

- ▶ Only insert the SD card when the device is in a de-energized state.
- ▶ Avoid write operations to SD cards. Reasons:
  - The number of write cycles possible on SD cards is limited.
  - A power failure during write operations will most likely lead to loss of data.
- ▶ Only remove the SD card when the device is in a de-energized state.
- ▶ Before switching off, ensure that no software write operations to the SD card are in progress.



#### Inserting the SD card

1 Push the SD card into the SD slot (A) until it snaps into position.

#### Removing the SD card

- 1 Push the SD card in the SD slot (A) all the way in.
  - This releases the lock mechanism and the SD card comes out of the SD slot a little.
- 2 Remove the SD card from the SD slot.

# 6 Operation

6.4 Inserting and removing an SD card

# 7 Maintenance and service

# 7.1 Safety regulations

Read Chapter 3 Safety regulations, 9 before working with the device. This contains important information for your personal safety.

#### 7 Maintenance and service

#### 7.2 Maintenance

#### 7.2 Maintenance

Devices with resistive touch are maintenance-free. However, the following work may be necessary:

- Cleaning of the resistive touch if contaminated.
- Recalibration of the resistive touch if it does not respond correctly to touch operation.

#### 7.2.1 Cleaning the resistive touch

#### **CAUTION**



#### Cleaning the device

Damage to the device due to the use of pointed or sharp objects or by liquids.

- ▶ Do not use any pointed or sharp objects (e.g. knife) for cleaning.
- ▶ Do not use any aggressive or abrasive cleaning agent or solvent.
- ▶ Avoid any liquid entering the device (risk of short-circuit).
- 1 Clean the resistive touch carefully with a clean, soft, damp cloth.
  - With stubborn contamination, spray a little cleaning agent onto the damp cloth first.

#### 7.2.2 Recalibrating a resistive touch

The resistive touch is already calibrated when delivered. However, it must be recalibrated if it does not respond correctly to touch operation. Touch calibration, see Document «MN05010007Z-EN System Description Windows CE».

#### 7.2.3 Battery

The integrated battery cannot be exchanged. Lifespan, see Chapter 9.4 System, 

50.

## 7.3 Service

## 7.3.1 Repairs

The device must only be opened by the manufacturer or by an authorized repair center.

Contact your local supplier or Eaton technical support for repairs.

Only the original packaging should be used for transporting the device.

# 7.4 Troubleshooting

# 7.4 Troubleshooting

Fault and possible cause	Corrective action
Device does not start (boot).	
Power supply interface does not have any power.	Check the power supply cable.
While the device is starting (booting), the following message appears:	
«<50> Touch is dirty or defect» (only appears if GALILEO is installed)	
Resistive touch is not correctly calibrated.	<ul> <li>Start (boot) the device.</li> <li>Calibrate touch         (→ Document «MN05010007Z-EN System Description Windows CE»).</li> </ul>
Device is faulty.	Send in your device for repair.
Display remains or becomes dark.	
Backlight is switched off.	Check the function in the visualization software.
Backlight is faulty.	Send in your device for repair.
Touch does not react or does not react correctly to touch operation.	
Resistive touch is not correctly calibrated.	<ul> <li>Start (boot) the device.</li> <li>Calibrate touch         (→ Document «MN05010007Z-EN System Description Windows CE»).</li> </ul>
Touch is deactivated.	<ul> <li>Start (boot) the device.</li> <li>Activate touch</li> <li>(→ Document «MN05010007Z-EN System Description Windows CE»).</li> </ul>
The icon 1 appears in the taskbar.	
Incorrect operation of the operating elements on the display.	Remove all objects from the area of the display.
Device is faulty.	Send in your device for repair.
<u> </u>	

Tab. 15 Troubleshooting

# 8 Storage, transport and disposal

## 8.1 Safety regulations

Read Chapter 3 Safety regulations, 

9 before installing and commissioning the device.

This contains important information for your personal safety.

## 8.2 Storage

The ambient conditions for storage must be fulfilled. See Chapter 9.9 Ambient conditions, 

53.

## 8.3 Transport

Damage to the device must be prevented during transport (use an appropriate packaging).

The ambient conditions must be fulfilled even when the device is transported. See Chapter 9.9 Ambient conditions, 

53.

1 Check the device on arrival for damage in transit.

## 8.4 Disposal

#### **⚠** DANGER



#### **Explosive and toxic materials**

Any improper handling causes a risk of explosion due to the lithium battery soldered in the device.

Dispose of the device properly.

Devices that are no longer used must be properly disposed of in accordance with the applicable national regulations or returned to the manufacturer or sales office.

# Materials used in the device

Component	Material
Housing	Galvanized sheet steel
Back plate	PC-GF
Resistive touch back panel	Glass with polyester foil
Battery	Lithium CR2032, 3.0 V, 220 mAh, Panasonic
Battery weight	3.4 g
SVHC Substance	1.2-dimethoxyethane: ethylene glycol dimethyl ether (EGDME)
Substance weight	2-4 %
Electronic components	Various

Tab. 16 Materials used in the device



The materials used for our housings are halogen-free.

# Materials used in the packaging

Packaging	Material
External packaging	Cardboard
Internal packaging	<ul><li>Cardboard</li><li>Plastic bag: Polyethylene (PE)</li></ul>

Tab. 17 Materials used in the packaging

# 9.1 Dimensions and weights

## 9.1.1 5.7" devices

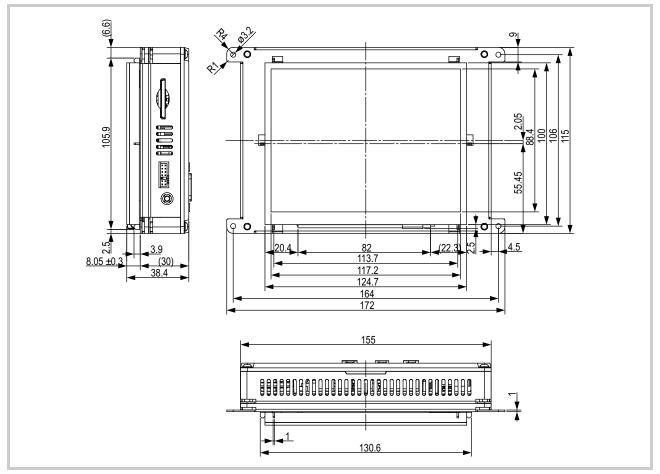


Abb. 18 Mechanical dimensions of the 5.7" devices in mm

Property	XV-112 5.7"
Height	115 mm
Width	172 mm
Depth	38.5 mm
Weight	Approx. 0.7 kg

Tab. 18 Dimensions and weights of the 5.7" devices

# 9.1 Dimensions and weights

#### 9.1.2 7.0" devices

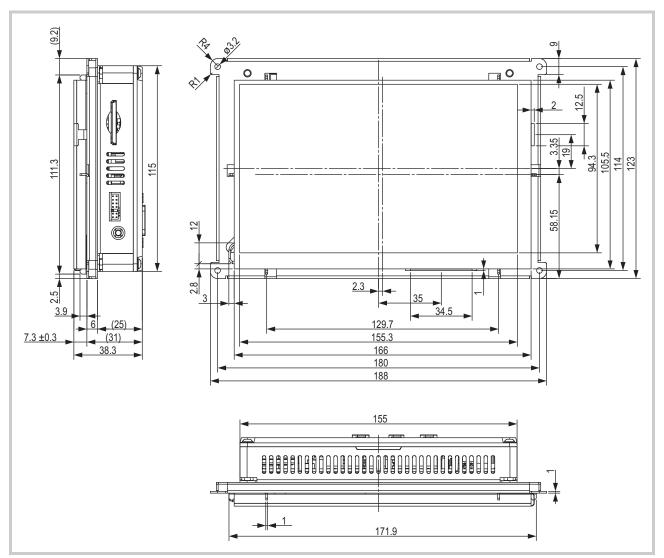


Abb. 19 Mechanical dimensions of the 7.0" devices in mm

Property	XV-112 7.0"
Height	123 mm
Width	188 mm
Depth	38.5 mm
Weight	Approx. 0.9 kg

Tab. 19 Dimensions and weights of the 7.0" devices

# 9.2 Display

Property	XV-112
Туре	TFT-LCD
Resolution (W × H)	
5.7" devices	VGA (640 × 480 pixels)
7.0" devices	WVGA (800 × 480 pixels)
Visible display area	
5.7" devices	115 mm × 86 mm (5.7" screen diagonal)
7.0" devices	152 mm × 91 mm (7.0" screen diagonal)
Color resolution	64k colors
Contrast ratio	Normally 300:1
Brightness	Normally 250 cd/m <sup>2</sup>
Backlight	
Technology	LED
Dimmable via software	
5.7" devices	100 % 30 % brightness
7.0" devices	100 % 20 % brightness
Lifespan	Normally 40 000 h
Resistive touch back panel	Touch sensor (glass with foil)

Tab. 20 Display

# 9.3 Touch sensor

Property	XV-112
Туре	Resistive touch
Technology	4-wire

Tab. 21 Touch sensor

# 9 Technical data9.4 System

# 9.4 System

Property	XV-112
Processor	RISC, 32-bit, 400 MHz
Internal memory	
DRAM	64 MByte
NAND Flash	64 MByte
NVRAM	125 KByte
NOR Flash	2 MByte
External memory	
SD memory card slot	1× SDA specification 1.00 Suitable for SD cards ( <b>not</b> for SDHC cards or cards of newer standard) Use only original accessories.
Real-time clock (battery backup)	
Battery type	CR2032 (190 mA/h), maintenance-free (soldered)
Backup time in de-energized state	Normally 10 years

Tab. 22 System

# 9.5 Interfaces

XV-112
100Base-TX / 10Base-T
USB 2.0, not electrically isolated
USB 2.0 (1.5 / 12 / 480 MBit/s), not electrically isolated
RS232, not electrically isolated
CAN, not electrically isolated Exception: The CAN interfaces of XV-112-DB are electrically isolated.
RS485, not electrically isolated
→ Chapter 9.5.1, 🗎 51
Only for service tasks
Only for service tasks

Tab. 23 Interfaces

## 9.5.1 Power supply

Property	XV-112
Rated voltage	24 VDC SELV (safety extra low voltage)
Permissible voltage	<ul> <li>RMS value: 19.2 30.0 VDC (rated voltage -20 % / +25 %)</li> <li>Absolute with ripple: 18.0 31.2 VDC</li> <li>Battery operation: 18.0 31.2 VDC (rated voltage -25 % / +30 %)</li> <li>35 VDC for a period &lt; 100 ms</li> </ul>
Voltage dips	<ul><li>10 ms from rated voltage (24 VDC)</li><li>5 ms from undervoltage (20.4 VDC)</li></ul>
Power consumption	
Basic device	Max. 7 W
USB stations on USB host	Max. 2.5 W
Total	Max. 9.5 W
Current consumption	
Continuous current	Max. 0.4 A (24 VDC)
Starting current inrush	1.5 A <sup>2</sup> s
Protection against reverse polarity	Yes
Fuse	Yes (replacement only by the manufacturer or by an authorized repair center)
Potential isolation	No

Tab. 24 Power supply

# 9.6 Enclosure ratings

Property	XV-112
Housing	IP20, Enclosure Type 1

Tab. 25 Enclosure ratings

# 9.7 Agency approvals and standards

# 9.7 Agency approvals and standards

Property	XV-112
EMC	2004/108/EC
Explosion protection	II 3D Ex tc IIIC T70°C IP6x (ATEX 94/9/EC):  Zone 22, category 3D <sup>1)</sup>
UL	UL 508, file no. E205091

Tab. 26 Agency approvals and standards

- 1) Zone 22, category 3D:
  - IP5x for devices of the group IIIB (non-conductive dust)
  - IP6x for devices of the group IIIC (conductive dust)

# 9.8 Applicable standards and regulations

Property	XV-112
EMC (in relation to CE)	
IEC/EN 61000-6-2	Immunity for industrial areas
IEC/EN 61000-6-4	Emission for industrial environments Devices meeting this standard may not be used in residential areas.
Explosion protection (in relation to CE)	
ATEX 94/9/EC: Zone 22, Category 3D	(II 3D Ex tc IIIC T70°C IP6x):
IEC/EN 60079-0	Explosive atmospheres: equipment - general requirements
IEC/EN 60079-31	Explosive atmospheres: equipment dust ignition protection by enclosure «t»
Safety	
IEC/EN 60950	Safety of information technology equipment
UL 508	Industrial control equipment (Engineering conditions of acceptability by UL, → Kapitel 5.2.1,   ⊇ 20)
Product standards	
EN 50178	Electronic equipment for use in power installations
IEC/EN 61131-2	Programmable logic controllers, equipment requirements and tests

Tab. 27 Applicable standards and regulations

# 9.9 Ambient conditions

Property	XV-112
Temperature	
Operation	0 50°C
Storage / Transport	-20 60°C
Relative air humidity	10 95%, non-condensing
Vibration in accordance with IEC/EN 60068-2-6	Displacement:  59 Hz: 3.5 mm  960 Hz: 0.15 mm  Acceleration:  60150 Hz: 2 g
Schock in accordance with IEC/EN 60068-2-27	15 g / 11 ms
Fall test	In accordance with IEC/EN 60068-2-31

Tab. 28 Ambient conditions

9.9 Ambient conditions